

⊕ Feature

- •Pair and triple wire coil for high stability and high balance.
- Available in tape & reel for automatic surface mounting.

Applications

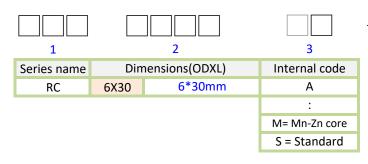
Double Balance Mixers.

Broad-Band Transformers.

Impedance Transformers.

Common Mode Filter, Balun Transformers.

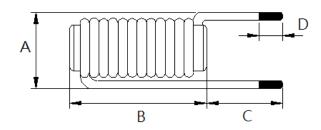
⊕ Product Identification:



	4		
Indu	uctance	Tolei	rance
1R0	1 μΗ	K	10%
100	10 μΗ	М	20%
101	100 μΗ	N	30%
102	1000 μΗ		Min

-	6
	Material
	K25=2500ui
	K70=7000ui
	T12=12000ui
	:

Shapes And Dimensions

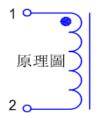


Part No.				Dimensi	ons(mm)
Part NO.	Α	В	С	D	
RC6x30MS-11TS	8.0	30.0	13.00	2.00	
KC0X30IVI3-1113	±2.0	±1.0	Тур.	Тур.	

Electrical Characteristics:

Part No.	Pin No	Turns	Wire	L (μH)	DCR	Hi-Pot
		(Ts)		1KHz/0.25V	(mΩ)	(N1)
RC6x30MS-11TS	N1	11.5	2UEW-0.6(本色)	5.6		AC - V, - mA, - Sec
				Тур.	Max.	366

⊕ Equivalent Circuit Schematic:



⊕ Material List:

No.	Location	Material
1	Core	MK25 R6x30
2	Wire	N1 :2UEW-130, 金色
3	Solder	Sn99.3 Cu0.7

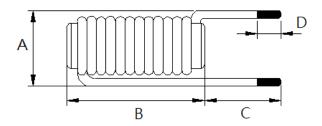


TEST DATA FOR PREPRODUCTION SAMPLES

Customer			Test Date			2016-5-23					
RSiN Part No.	F	C6x30MS-11T	S		Sample	Quantity	,		10		PCS
Lot No			Test Temp	25	°C			Test H	umidity	62	2%
MEAS	L(N1)	DCR(N1)		А	В	С	D	Е	G		
Item	(μH)	(m Ω)		(mm)	(mm)	(mm)	(mm)	(mm)	(mm)		
SPEC	5.6	0		8.00	30.00	13.00	2.00	-	_	_	-
Upper	-	0.00	-	10.00	31.00	-	1	-	-	-	-
Lower	-	-	-	6.00	29.00	-	•	-	-	-	-
Tolerance	Тур	Max		2.00	1.00	Тур	Тур	-	-	-	-
Test Freq.	1KHz/0.25V									-	-
1	5.60			8.74	29.70	13.10	2.00				
2	5.60			8.86	29.72	13.12	2.00				
3	5.62			8.78	29.70	13.08	2.00				
4	5.55			8.82	29.74	13.06	2.00				
5	5.62			8.78	29.70	13.08	2.00				
6											
7											
8											
9											
10											
Average	5.60			8.80	29.71	13.09	2.00				
Max	5.62	0.00		8.86	29.74	13.12	2.00	0.00	0.00	0.00	0.00
Min	5.55	0.00		8.74	29.70	13.06	2.00	0.00	0.00	0.00	0.00
Range	0.07	0.00		0.12	0.04	0.06	0.00	0.00	0.00	0.00	0.00
StDevP	0.03	#DIV/0!		0.04	0.02	0.02	0.00	######	######	######	######

Test Instrument

LCR CHROMA 3302A
DCR TH283TLX+TH1901A



Coil Spec: 2UEW-0.6mm*11Ts

Drawn by Checked by Approved by

davy amanda Vincent



⊕ General Characteristics

項目 Item	Conditions	Specification
温度特性 Temperature drift	在温度-25~+ 85℃之间测试。 To be measured in the range of -25℃ to 85℃.	Inductance temperature coefficient 2000 ppm/°C or less
保存温度范围 Storage Temperature	在包装的状态下。 With taping.	- 25°C ~ +85°C
使用温度范围 Operating Temperature	包括制品的发热温度。 Including self temperature rise.	- 25°C ~ +85°C
弯曲测试 Bending test	试件焊接在基板上,按箭头方向以大约0.5mm/秒的速度加压,直到基板变形幅度到3mm 保持30 秒。 Apply pressure gradually in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. Pressing device ■ ■ 基板Board: 40*100mm 厚Thickness: 1.0mm ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm and hold for 30±5s. ■ Inches in the arrow at a rate of about 0.5mm/s until bent depth reaches 3mm/s unt	Change from an initial value L : within±10%
固着强度 Adhesion strength	按箭头方向用R0.5 的加压棒在试件中施加一定的静力并保持60±5秒. A static load using a R0.5 pressing tool shall be applied the arrow and to the body of the specimen in the direction of the arrow and shall be hold for 60±5s. Measure after removing pressure. Specimen 1st 5N 2nd 5N	Change from an initial value L : within±10%



耐振性 Vibration	振动频率10~55~10Hz, 振幅1.5mm, 分X,Y,Z 方向各振动1 小时(共3 小时)。 The specimen shall be subjected to a vibration of 1.5mm amplitude, sweep frequency 10~55Hz (10Hz to 55Hz to 10Hz in a period of one minute) for 1 h in each of 3(X,Y,Z) axes.	Change from an initial value L : within±10%
耐冲击性 Mechanical shock	利用橡胶块式落下冲击试验机,分别在3 个互相垂直的方向以981m/S2 的冲击加速度落下。 Peak acceleration: 981 m/S2 Duration of pulse: 6ms 3 times in each of 3(X,Y,Z)axes. The specimen must be fixed on test board. Three successive shock shall be applied in the perpendicular direction of each surface of the specimen.	Change from an initial value L : within±10%
自然落下试验 Free fall test	试件安装在基板上,并固定在重500 克的盒中,由1 米高自由落体,3 个互相垂直的方向各3次。 The specimen must be fixed on test board. It must be equipped with instruments of which weight is 500g. Then it shall be fallen freely from 1m height to rigid wood 3 times in each of three axes.	L. Within ± 1070
焊锡付着性 Solder ability	seconds in hax at room temperature. Dip	90%以上的面积要被 覆盖。 New solder shall cover 90% minimum of the surface immersed.
耐电压 Dielectric strength	在电极与磁材之间加入直流电压100V 通电时间 1 分钟。 100V DC shall be applied for 60s between the terminal and the core.	没有损害。 Without damage.



焊锡耐热性 Resistance to soldering heat	试验方法Test method 热风炉焊接Reflow soldering method 预热Preheat 150~180℃ 90±30s 峰值温度Peak temp 250(+ 5,-0)℃ (230℃min, 30±10s) 试验板的厚度0.8mm 上按上面条件通过两次热 风炉。 The specimen shall be subjected to the reflow process under the above condition 2 times.Test board shall be 0.8mm thick. Base material shall be glass epoxy resin. 测定Measurement	Change from an initial value L : within±10%
	常温常湿中放置于1 小时以上测试。 The specimen shall be stored at standard atmospheric conditions for 1 h in prior to the measurement.	
	在电极与磁材之间加入直流电压100V。	
绝缘抵抗 Insulation resistance	100V DC shall be applied between the terminal and the core.	100mΩ以上 100mΩ or more.
	在温度-40±3℃中放置500±12 小时后·常温常湿中放置1 小时以上2 小时以内测试。	
耐寒性 Low temperature	The specimen shall be stored at a temperature of -40±3°C for 500 ±12h. Then it shall be stabilized under standard atmospheric conditions for 1 h before measurement Measurement shall be made within 1h.	Change from an initial value L : within±10%
耐热性 Dry heat	在温度85±2℃中放置500±12 小时后,常温常湿中放置1 小时以上2 小时以内测试。	
	The specimen shall be stored at a temperature of 85 ± 2°C for 500± 12h. Then	



耐湿性 Dump heat	humidity of 90 ~ 95% for 500 ± 2h. Then it shall be stabilized under standard atmospheric conditions for 1 h before measurement. Measurement shall be made within 1h.	Change from an initial value L : within±10%
温度循环 Temperature cycle	Icontinuous cycles of temperature change of 1	Change from an initial value L : within±10%

标准状态Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions in making measurements and test as follows;

Ambient temperature: 5°C to 35°C, Relative humidity: 45% to 85%, Air pressure: 86kPa to 106kPa

If more strict measurement is required, measurement shall be made within following limits; Ambient temperature: 20±2°C, Relative humidity: 65±5%, Air pressure: 86kPa to 106kPa

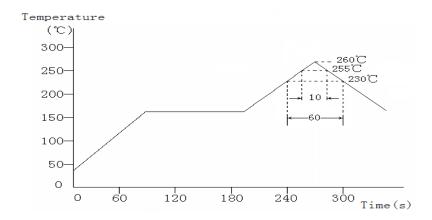
禁用物质Prohibited Subtances

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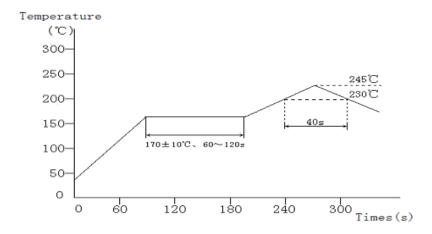


⊕ Reflow Soldering Heat Endurance



- □No mechanical and electrical defects are found after testing based on the above profile and keeping under the conditions of room temperature and humidity for 2 hours.
- □Twice reflow test is acceptable with the test interval remaining 1 hour under the normal conditions.
- □The reflow test profile may vary with the testing instruments.

⊕ Recommended Reflow Conditions



The recommended reflow profile is based on the testing instruments used. Solder ability will depend on the testing equipments, reflow conditions, testing method, etc. So it is necessary to make a confirmation of them when the reflow conditions are set up.